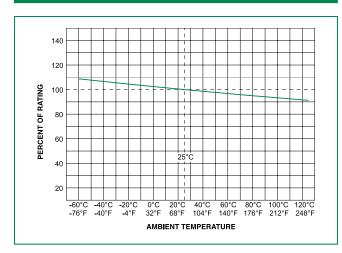


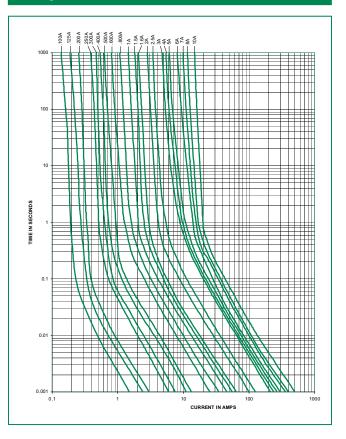
Temperature Re-rating Curve



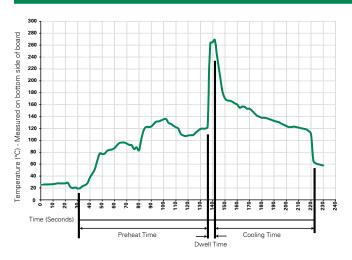
Note:

1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation	
Preheat:		
(Depends on Flux Activation Temperature)	(Typical Industry Recommendation)	
Temperature Minimum:	100°C	
Temperature Maximum:	150°C	
Preheat Time:	60-180 seconds	
Solder Pot Temperature:	260°C Maximum	
Solder DwellTime:	2-5 seconds	

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.

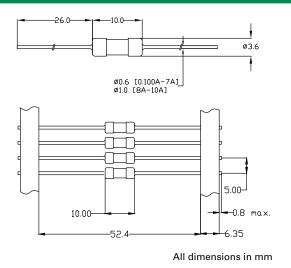


Product Characteristics

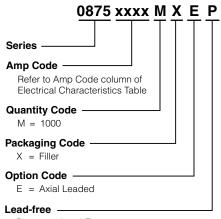
Materials	Body: Ceramic Cap: Nickel Plated Brass Tin Plated Copper	
Terminal Strength	MIL-STD-202, Method 211, Test Condition A	
Solderability	MIL-STD-202, Method 208	
Product Marketing	Body: Brand Logo, Current Rating Characteristic "T", Agency approval marks	
Packaging	Bulk (1000 pcs/pkg) Tape & Reel (1000 pcs/reel)	

Operating Temperature	-55°C to 125°C	
Thermal Shock	MIL-STD-202, Method 107 Test Condition B3 (5 cycles -65°C to +125°C)	
Vibration	MIL-STD-202, Method 201 (10-55 Hz)	
Humidty	MIL-STD-202, Method 106, High Humidity (90-98%RH), Heat (65°C)	
Salt Spray	MIL-STD-202, Method 101, Test Condition B	

Dimensions



Part Numbering System



P = Lead-Free Others = Special Options

Please call Littelfuse for detail

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	Taping Width	
875 Series					
Bulk	Bulk	1000	MXE	N/A	
Tape and Reel	EIA 296	1000	MRET1	T1 = 52mm (2.062")	